WHAT IS CLAIMED IS

1. A package structure, comprising:

a first insulation layer, wherein at least one first conductive via is formed in the first insulation layer;

a first conductive layer disposed on a top surface of the first insulation layer and in contact with the at least one first conductive via;

a direct bond copper substrate comprising a second conductive layer, a third conductive layer and a ceramic base, wherein the ceramic base is disposed on a bottom surface of the first insulation layer and exposed to the first insulation layer by a press-fit operation and comprises a first side surface and a second side surface opposite the first side surface exposed to surroundings, the second conductive layer is disposed on a top surface of the ceramic base and embedded within the first insulation layer, and the third conductive layer is disposed on a bottom surface of the ceramic base; and

at least one first electronic component embedded within the first insulation layer and attached on the second conductive layer through a fixing material, wherein the first electronic component comprises at least one first conducting terminal, and the at least one first conducting terminal is electrically connected with the second conductive layer and/or electrically connected with the first conductive layer through the at least one first conductive via.

2. The package structure according to claim 1, further comprising a first heat dissipation device located at an outer side of the third conductive layer.

3. The package structure according to claim 1, wherein a length of the third conductive layer in a horizontal direction is shorter than a length of the ceramic base in the horizontal direction, and the third conductive layer is located at a substantially middle region of the bottom surface of the ceramic base.

pattern, and a second end of the second conductive via is in contact with the corresponding second conductive pattern.

9. A package structure, comprising:

a first insulation layer, wherein at least one first conductive via is formed in the first insulation layer;

a first conductive layer disposed on a top surface of the first insulation layer and in contact with the at least one first conductive via, wherein the first conductive layer comprises at least one first conductive pattern;

a direct bond copper substrate comprising a second conductive layer, a third conductive layer and a ceramic base, wherein the ceramic base is disposed on a bottom surface of the first insulation layer and exposed to the first insulation layer by a press-fit operation, the second conductive layer is disposed on a top surface of the ceramic base and embedded within the first insulation layer, and the third conductive layer is disposed on a bottom surface of the ceramic base;

at least one first electronic component embedded within the first insulation layer and attached on the second conductive layer through a fixing material, wherein the first electronic component comprises at least one first conducting terminal, and the at least one first conducting terminal is electrically connected with the second conductive layer and/or electrically connected with the first conductive layer through the at least one first conductive via; and

~~The package structure according to claim 5, further comprising~~ a plurality of pins, wherein the pins are disposed on and in contact with the corresponding first conductive patterns.

10. The package structure according to claim 9, further comprising at least one second electronic component, wherein the second electronic component is disposed on the first conductive layer and arranged between the pins, wherein the second electronic component comprises at least one second conducting terminal, and the second conducting terminal is disposed on the corresponding first conductive pattern.

11. The package structure according to claim 10, wherein the pin comprises:

an insertion part; and

a sustaining part, wherein a first end of the sustaining part is disposed on the corresponding first conductive pattern, and a second end of the sustaining part is connected with the insertion part, wherein a width of the sustaining part is larger than a width of the insertion part.

12. The package structure according to claim 11, wherein an overall height of the sustaining part with respect to the first conductive layer is larger than an overall height of the second electronic component with respect to the first conductive layer.

13. The package structure according to claim 9, further comprising:

a first insulative heat-dissipating layer disposed on the first conductive layer and covering the first conductive layer; and

a second heat dissipation device located at an outer side of the first insulative heat-dissipating layer for enhancing heat dissipating efficacy of the first conductive layer.

14. The package structure according to claim 13, wherein the pins are disposed on a part of the first conductive layer that is uncovered by the first insulative heat-dissipating layer, wherein the second heat dissipation device is arranged between the pins.

15. ~~The package structure according to claim 5, further comprising:~~A package structure, comprising:

a first insulation layer, wherein at least one first conductive via is formed in the first insulation layer;

a first conductive layer disposed on a top surface of the first insulation layer and in contact with the at least one first conductive via, wherein the first conductive layer comprises at least one first conductive pattern;

a direct bond copper substrate comprising a second conductive layer, a third conductive layer and a ceramic base, wherein the ceramic base is

disposed on a bottom surface of the first insulation layer and exposed to the first insulation layer by a press-fit operation, the second conductive layer is disposed on a top surface of the ceramic base and embedded within the first insulation layer, and the third conductive layer is disposed on a bottom surface of the ceramic base;

at least one first electronic component embedded within the first insulation layer and attached on the second conductive layer through a fixing material, wherein the first electronic component comprises at least one first conducting terminal, and the at least one first conducting terminal is electrically connected with the second conductive layer and/or electrically connected with the first conductive layer through the at least one first conductive via;

a second insulation layer disposed on the first conductive layer and covering the first conductive layer, wherein the second insulation layer comprises at least one fourth conductive via;

a fourth conductive layer disposed on a top surface of the second insulation layer and in contact with the at least one fourth conductive via; and

a third electronic component embedded within the second insulation layer and attached on the first conductive layer through the fixing material, wherein the third electronic component comprises at least one third conducting terminal, and the at least one third conducting terminal is electrically connected with the first conductive layer and/or electrically connected with the fourth conductive layer through the at least one fourth conductive via.

16. The package structure according to claim 15, wherein the fourth conductive layer comprises at least one fourth conductive pattern, the third electronic component has a top surface and a bottom surface, the third conducting terminal formed on the top surface of the third electronic component is in contact with the corresponding fourth conductive via, and the third conducting terminal formed on the bottom surface of the third electronic component is disposed on the first conductive layer and electrically connected with the first conductive layer.